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PRIMA-BOND
ME7250-5

Molecularly Extra-Flexible
Low Viscosity
Solvent-Free
Insulating
Extra Clean in Ionics

IDEAL FOR:

High Temperature Curing
Extra-Flexibility
Automated Assembly
Extra Large Area Bonding
High Transparency

DESCRIPTION:

ME7250-5 is a EXTRA-FLEXIBLE insulating epoxy adhesive for large area bonding applications. This paste is solvent free. It is designed for automated, inline bonding processing. Its flexibility helps to absorb interfacial stresses for long-term reliability.ME7250-5 may be packaged into Part A and Part B in equal volume and weight for ease of storage and transport.

ME7250-5 is low in ionic impurities with extra flexibility for extreme temperature cycling and extra large area bonding.

AVAILABILITY:

ME7250-5 is available in syringes for automatic needle dispense applications or in jars. ME7250-5 is available for packages in A and B Part for ambient storage and transport

APPLICATION PROCEDURES:

(1) Thaw for 30 minutes before opening jar or using syringes.

(2) Dispense adhesive onto clean substrate with a suitable pattern to assure full die coverage.

(3) Cure according to one of the recommended cure schedules.

TYPICAL PROPERTIES*

Electrical Resistivity (150ºC/ 30 min)	**>1x10^{14} ohm-cm**
Dielectric Strength (Volts/mil)	**>750**
Glass Transition Temp.(ºC)	**-55 ±10%**
Current Carrying Capabilities	
Lap-Shear Strength	**>200 psi** **>1.35 N/mm^2**
Device Push-off Strength	**>600 psi** **>4.1 N/mm^2**
Hardness (Type)	**30 (A) ±10%**
Cured Density (gm/cc)	**1.1 ±10%**
Thermal Conductivity	**1.4 Btu-in/hr-ft^2-ºF ±10%** **0.20 W/m-ºC ±10%**
Linear Thermal Expansion Coeff. (ppm/ºC)	**120 ±15%**
Maximum Continuous Operation Temp. (ºC)	**<150**
Pot Life	**5 days**
Avg. Viscosity(5.0 rpm, 25ºC) (Brookfield DV-1,Spindle CP51)	**8,000 cp ±20%**
Thixotropic Index	**2.0±20%**

* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

CURE SCHEDULES:

Temperature	Time	Pressure
80ºC	>16 hr	
100ºC	>6 hr	
150ºC	90 min	
200ºC	10 min	

Ambient floor life (pot-life) is 5 days or more.

When packaged in A and B Parts, please mix by equal weight or equal volume and degas until quiet before use.

SHELF LIFE:

Storage temperature	Shelf Life
-40ºC	12 mo (PRE-MIXED
Ambient	12 mo (A and B Part Pa

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details.

PRODUCT DATA SHEET **Ver 2.1 07/18/2023**